

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|----------------------------|---------------------|
| 1 | 29 | (UBM or (under adj bump adj metallurgy)) and (polyimide with (opening or mask)) | USPAT; US-PGPUB | 2003/07/09 15:42 |
| 2 | 1 | (UBM or (under adj bump adj metallurgy)) and (polyimide with (opening or mask)) | EPO; JPO; DERWENT; IBM TDB | 2003/07/09 13:51 |
| 3 | 9 | (taiwan adj semiconductor) and (UBM or (under adj bump adj metallurgy)) and polyimide | USPAT; US-PGPUB | 2003/07/09 14:43 |
| 4 | 4 | ((taiwan adj semiconductor) and (UBM or (under adj bump adj metallurgy)) and polyimide) not ((UBM or (under adj bump adj metallurgy)) and (polyimide with (opening or mask))) | USPAT; US-PGPUB | 2003/07/09 14:42 |
| 5 | 0 | (taiwan adj semiconductor) and (UBM or (under adj bump adj metallurgy)) and polyimide | EPO; JPO; DERWENT | 2003/07/09 14:43 |
| 6 | 108 | sputtering with (UBM or (under adj bump adj metallurgy)) | USPAT; US-PGPUB | 2003/07/09 15:02 |
| 7 | 57 | (sputtering with (UBM or (under adj bump adj metallurgy))) and @ad<=20010215 | USPAT; US-PGPUB | 2003/07/09 15:43 |
| 8 | 92 | (UBM or (under adj bump adj metallurgy)) and stencil | USPAT; US-PGPUB | 2003/07/09 15:43 |
| 9 | 50 | ((UBM or (under adj bump adj metallurgy)) and stencil) and @ad<=20010215 | USPAT; US-PGPUB | 2003/07/09 15:55 |
| 10 | 50 | ((UBM or (under adj bump adj metallurgy)) and stencil) and @ad<=20010215 | USPAT; US-PGPUB | 2003/07/09 16:05 |
| 11 | 23 | ((UBM or (under adj bump adj metallurgy)) and stencil) and @ad<=20010215) and screen | USPAT; US-PGPUB | 2003/07/09 16:05 |

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|-------------|------|--|----------------------------------|---------------------|
| 1 | 70 | (UBM or (under adj bump adj metallurgy)) and (etching with pad) | USPAT; US-PGPUB | 2003/07/09 18:12 |
| 2 | 33 | ((UBM or (under adj bump adj metallurgy)) and (etching with pad)) and @ad<=20010215 | USPAT; US-PGPUB | 2003/07/09 18:10 |
| 3 | 4 | (UBM or (under adj bump adj metallurgy)) and (etching with pad) | EPO; JPO; DERWENT; IBM TDB | 2003/07/09 18:13 |